

FIGURE 1
PRIOR ART

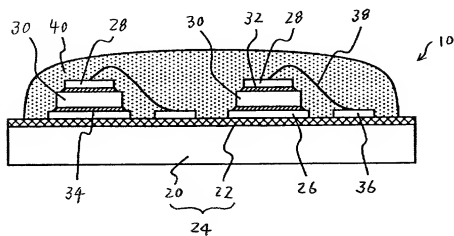


FIGURE 2
PRIOR ART

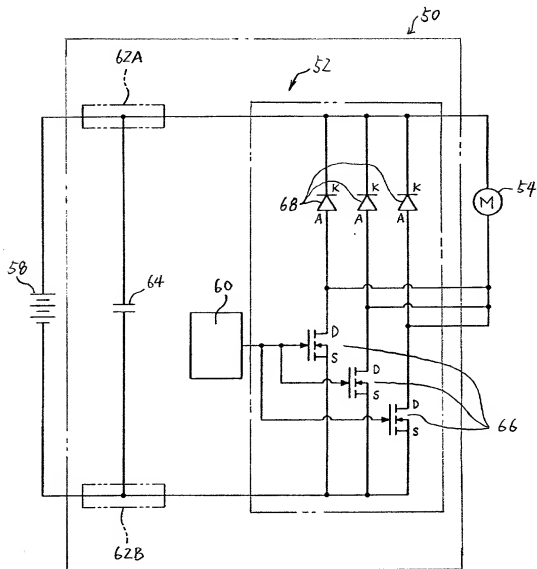


FIGURE 3

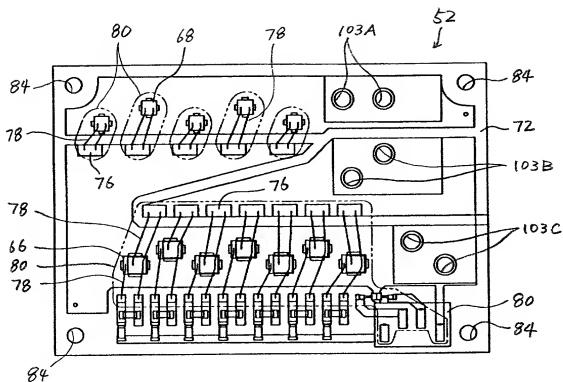


FIGURE 4

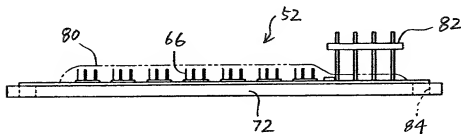


FIGURE 5

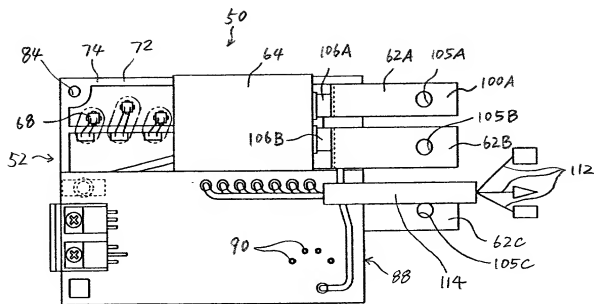


FIGURE 6

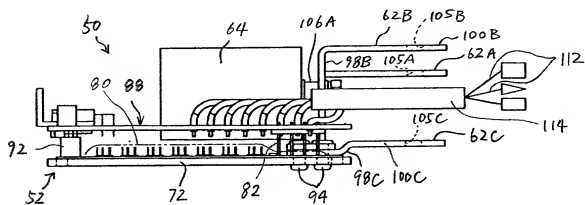


FIGURE 7

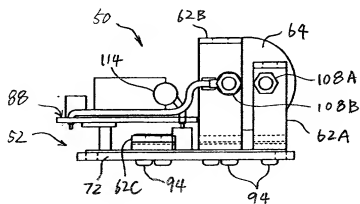


FIGURE 8

10622297.121201

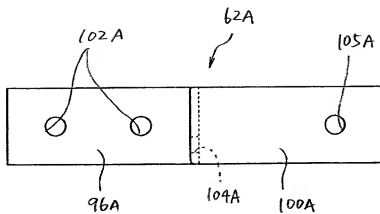


FIGURE 9

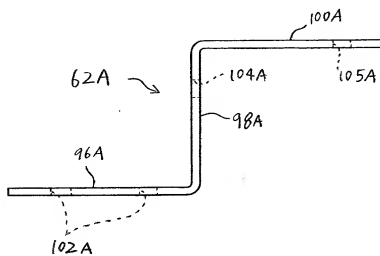


FIGURE 10

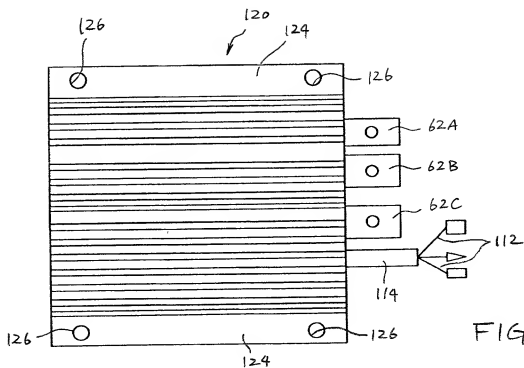


FIGURE 11

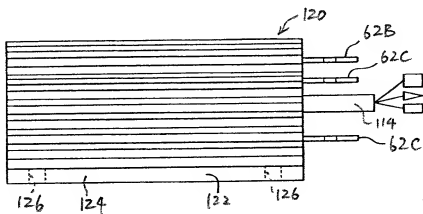


FIGURE 12

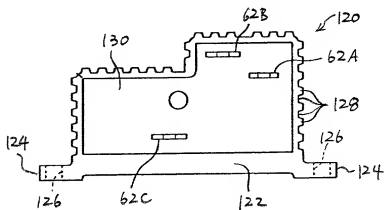


FIGURE 13

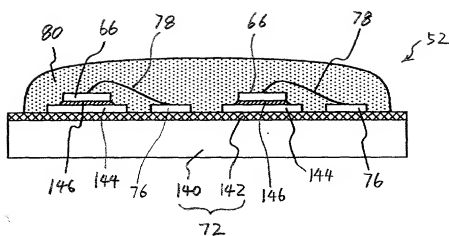


FIGURE 14

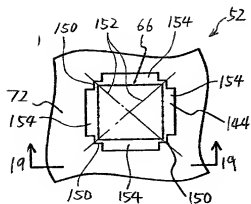


FIGURE 15

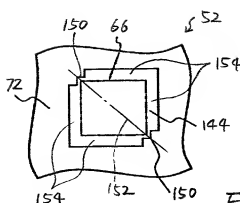


FIGURE 16

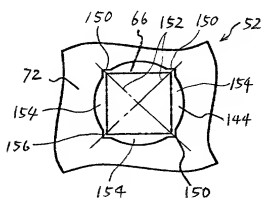


FIGURE 17

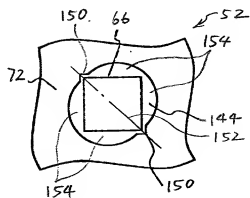


FIGURE 18

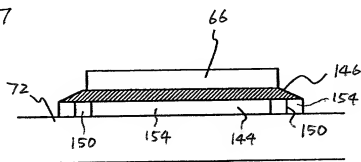


FIGURE 19

REFLOW SOLDERING DEVICE

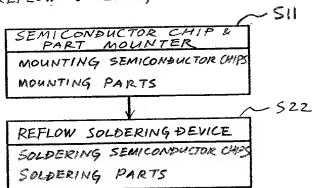


FIGURE 20

REFLOW SOLDERING DEVICE

+ DIE BONDER

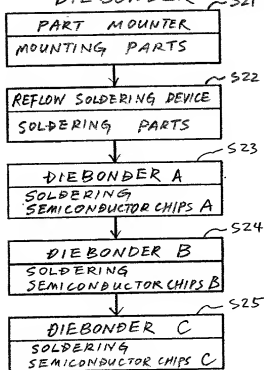


FIGURE 21

REFLOW SOLDERING DEVICE (USING MOUNTING JIG FOR SEMICONDUCTOR CHIPS)

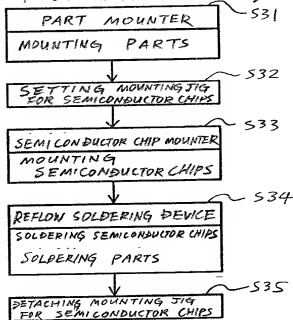


FIGURE 22

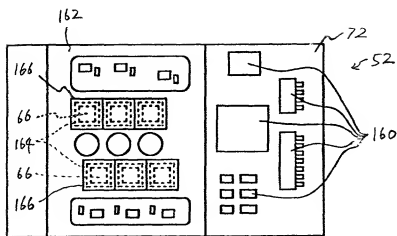


FIGURE 23

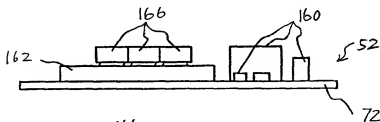


FIGURE 24

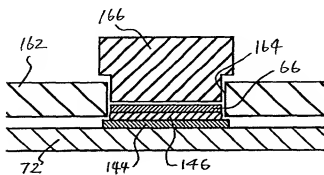


FIGURE 25

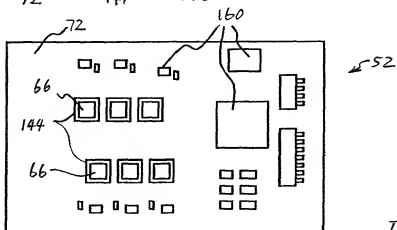


FIGURE 26